Inventor:

John T. Moore et al.

Title:

Semiconductor Wafer Assemblies Comprising Photoresist Over

Silicon Nitride Materials

Assignee:

Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT PURSUANT TO 37 C.F.R. " 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is

directed to the United States patents and other references listed on the attached

Form PTO-1449. No admission is made regarding whether all the submitted

references are prior art.

The listed references were cited by, or submitted to, the Office in the

parent, co-pending application of the above-identified application. The above-

identified application is a continuation application of co-pending application

Serial No. 09/995,372, filed November 26, 2001. Such prior disclosure is

sufficient for the above-identified application as far as copies of the references

are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Respectfully submitted,

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Dated: December 11, 2003

By:

Jennifer J. Taylor, Ph.D.

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Form PTO-1449	•					ENT OF COMMERCE ADEMARK OFFICE	ATTY. DOCKET NO M122-2463		PRIORITY SERIAL NO. 09/995,372				
		LIST	OF ART CITED (Use several sheets		CANT		APPLICANT John T. Moore et al.						
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					U.S. PA	TENT DOCUMENTS							
*Examiner Initial		Docu Numl		Date		Name		Class	Sub	class	Filing Date If Appropriate		
	AA	5,219	,788	6/93	Abernathey	et al.							
	AB	5,045	,847	9/91	Tarui et al.								
	AC	5,045	,345	9/91	Singer								
	AD	4,996	,081	2/91	Ellul et al.		_						
	AE	3,884	,698	5/75	Kakihama et	al.							
	AF	5,518	,946	5/96	Kuroda								
	AG	5,489	5,489,542 2/96 [wai et al.					-					
	AH	4,330	,569	5/82	Gulett et al.					. i			
	Al	4,499	,656	2/85	Fabian et al.								
	AJ	5,554	,418	9/96	Ito et al.								
	AK	5,926	,739	7/99	Rolfson et a	colfson et al.				:			
					FOREIGN	PATENT DOCUMENTS		<u> </u>	<u> </u>				
		Docu Numl		Date		Country		Class	Sub	class	Trans	lation	
	AL	4010	86562	3/89	Japan						Yes	No	
	AM		37854	6/87	Japan								
	AN	2129		5/84	Great Britain							- 111	
	AO	2170	549	8/86	Great Britain								
	AP	2145	243	3/85	Great Brit	ain							
	AQ	4030	75158	3/91	Japan								
				OTHER REFE	RENCES (includ	ing Author, Title, Date, I	Pertinent Pages, Etc.)						
	AR		Silicon Proc. for V	LSI; 177-178; V	ol. 1; S. Wolf								
						•							
	AS		Silicon Proc. for VLSI; 191-193; Vol. 1; S. Wolf										
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					U.S. PATENT DOCUMENTS	-				**		
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	AA	4,874	1,716	10/89	Rao						<u> </u>	
	AB	5,587	7,344	12/96	Ishikawa							
	AC	4,439	9,270	3/84	Powell et al.			,				
	AD	5,773	3,325	6/98	Teramoto							
	AE	5,904	1,523	5/99	Feldman et al.		:					
	AF	5,891	1,793	4/99	Gardner et al.							
	AG	5,795	5,821	8/98	Bacchetta et al.							
	AH	5,918	3,147	6/99	Filipiak et al.							
	AI	5,882	2,978	3/99	Srinivasan et al.							
	AJ	4,612	2,629	9/86	Harari							
	AK	5,831	1,321	11/98	Nagayama							
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				OTHER REFE	RENCES (including Author, Title, Date,	Pertinent Pages, Etc.)						
	AR		Silicon Proc. for V	LSI; 37-38; 598-	599; Vol. 2; S. Wolf					-		
						-						
	AS		Electronic Materials	Science: For In	tegrated Circuits; 1990 © ; Mayer et a	l; pp. 269-274; Pub. 19	90				_	
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*Examiner Initial		Docu Num	iment ber	Date		Name		Class	Sut	oclass	Filing Date		
	AA	3,549	9,411	12/70	Bean		7 X. W. W.						
	AB	4,440	5,194	5/84	Candelaria								
	AC	4,48	5,553	12/84	Christian								
	AD	4,543	3,707	10/85	Ito et al.								
	AE	5,098	3,865	3/92	Machado et	al.	al.						
	AF	5,160),998	11/92	Itoh et al.								
	AG	5,300	5,946	4/94	Yamamoto		· · · · · · · · · · · · · · · · · · ·						
	AH	5,442	2,223	8/95	Fujii	··· · <u> </u>	_ ,_						
-	Al	5,523	3,616	6/96	Den	Den			,				
	AJ	5,750	5,404	5/98	Friedenreich et al.								
	AK	5,834	1,374	11/98	Cabral Jr. et al.							•	
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				OTHER REFE	RENCES (includ	ing Author, Title, Date, I	Pertinent Pages, Etc.)						
	AR		Intrinsic Stress in S Insulation, Boston,			ide Films Prepared by ' Canicki, J. et al.	Various Deposition Tech	nniques; 1988	IEEE	Internati	. Sympos. On	Electrical	
					- 17.	<u> </u>		_		-			
	AS		Passivation of GaA 1988; pp. 1412-141		CVD Silicon Ni	tride Films of Different	Stress States; IEEE Tra	ansactions on	Electro	on Devic	es; Vol. 35, N	o. 9; Sept.	
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	AA	4,695	5,872	9/87	Chatterjee										
	AB	5,178	3,016	1/93	Dauenhauer	et al.									
	AC	5,985	5,771	11/99	Moore et al								_		
	AD	3,649	9,884	3/72	Haneta										
	AE	4,868	3,632	9/89	Hayashi										
	AF	5,304	1,829	4/94	Mori et al.	iori et al.									
,	AG	5,925	5,494	7/99	Hom	n						÷			
	AH	4,075	5,367	2/78	Gulett				·			\ <u>-</u>			
	AI	4,732	2,858	3/88	Brewer et al.										
	AJ	6,300	0,253	10/01	Moore, John T.										
-	AK	4,698	3,787	10/87	Mukherjee et al.							* .			
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				OTHER REFER	RENCES (includ	ling Author, Title, Date,	Pertinent Pages,	Etc.)							
	AR		Silicon Nitride Ove	ercoats for Thin I	Film Magnetic	Recording Media; IEEE	Transactions of	on Magne	tics; Vol 27.	No. 6,	Nov. 19	991; pp. 5070-	5072		
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	AA	4,939	,559	07/90	DiMaria et al.						
,	AB	6,1,40.	,181	10/00	Forbes et al.						
	AC	6,143	,627	11/00	Robinson						
	AD	5,877	,069	03/99	Robinson						
	AE	6,093	,956	07/00	/00 Moore et al.						
	_ AF	6,103,619 08/00 Lai					1				
	, AG	6,265	,241 .	07/01	Pan					·	
-,	АН	6,420	,777		Lam et al.	· ·					
	_ Al	6,417	,559	07/02	Moore et al.						
	, AJ	5,041	,888	08/91	Possin et al.						
	- AK	6,143	,662	11/00	Rhodes et al.		1				
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